MATERIAL: HOUSING: HIGH TEMPERATURE THERMAL PLASTIC. CONTACT: COPPER ALLOY.

PLATING: CONTACT: 0.30um MIN Pd/Ni , 0.05um MIN GOLD PLATING AT CONTACT AREA, GOLD FLASH AT SOLDER AREA. 2um MIN. NICKEL UNDER PLATING.

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   HOUSING: HIGH TEMPERATURE THERMAL PLASTIC. CONTACT: COPPER ALLOY.

2. PLATING:
   CONTACT: 0.30um MIN Pd/Ni , 0.05um MIN GOLD PLATING AT CONTACT AREA, GOLD FLASH AT SOLDER AREA. 2um MIN. NICKEL UNDER PLATING.

3. COPLANARITY: 0.10mm MAX.

4. RECOMMENDED THICKNESS OF METAL MASK FOR SOLDER: 0.10mm MIN.

5. INDICATED DATE CODE MARK.

2286981-1: AS SHOWN